



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPD60R385CP	Issued	27. April 2022
MA#	MA005730038		
Package	PG-TO252-3-35	Weight*	324.43 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.064	1.56	1.56	15611	15611
leadframe	inorganic material	phosphorus	7723-14-0	0.053	0.02		164	
	non noble metal	iron	7439-89-6	0.177	0.05		546	
	non noble metal	copper	7440-50-8	176.899	54.55	54.62	545262	545972
wire	non noble metal	aluminium	7429-90-5	0.649	0.20	0.20	2001	2001
encapsulation	organic material	carbon black	1333-86-4	0.401	0.12		1236	
	plastics	epoxy resin	-	15.642	4.82		48215	
	inorganic material	silicondioxide	60676-86-0	117.652	36.26	41.20	362644	412095
leadfinish	non noble metal	tin	7440-31-5	3.834	1.18	1.18	11816	11816
solder	non noble metal	tin	7440-31-5	0.081	0.02		250	
	noble metal	silver	7440-22-4	0.101	0.03		313	
	non noble metal	lead	7439-92-1	3.874	1.19	1.24	11942	12505
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com